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(54) **Title**: STACKED-CHIP PACKAGES IN PACKAGE-ON-PACKAGE APPARATUS, METHODS OF ASSEMBLING SAME, AND SYSTEMS CONTAINING SAME

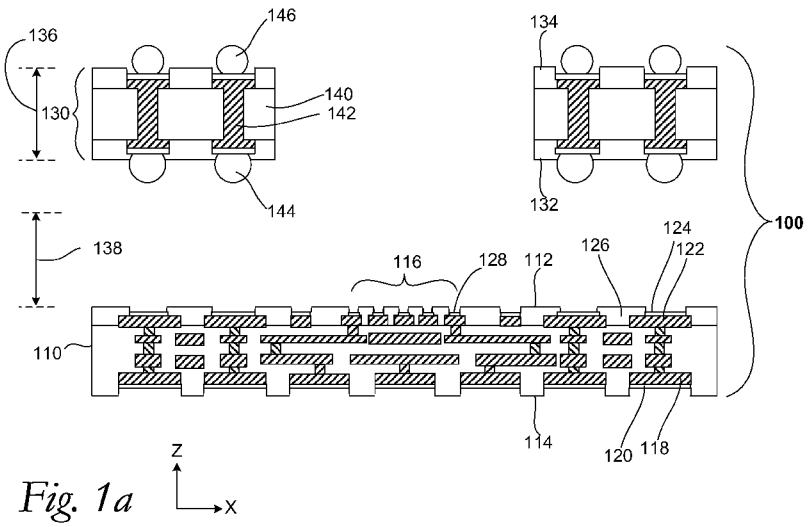


Fig. 1a

(57) **Abstract**: A stacked-chip apparatus includes a package substrate and an interposer with a chip stack disposed with a standoff that matches the interposer. A package-on-package stacked-chip apparatus includes a top package disposed on the interposer.

WO 2010/151375 A1